

# TP(P12)Mini2 GB



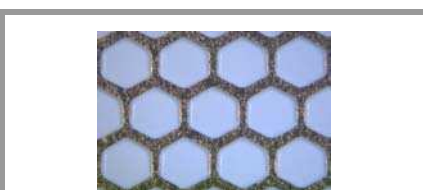
MiniSKiiP®

Pre applied thermal paste  
Wacker P12 (silicone based)

## TP(P12)Mini2 GB

### Features

- Honeycomb structure
- Optimized thickness of thermal paste layer
- Enhanced heat dissipation
- High process reliability due to automated screen printing process



honeycomb structure

Characteristics					
Symbol	Conditions	min.	typ.	max.	Unit
<b>Characteristics of printing process</b>					
$d_{tp}$	thickness of thermal paste (after assembly)	29	35	41	$\mu\text{m}$
<b>Storage conditions</b>					
$t_{stg}$	storage time			18	month
$T_{stg}$	storage temperature	-25		60	$^{\circ}\text{C}$
$RH_{stg}$	storage humidity	10		95	%
<b>Characteristics of thermal paste</b>					
$\gamma_{tp}$	specific gravity		2.25		$\text{g}/\text{cm}^3$
$R_{tp}$	resistivity		$1 \cdot 10^{13}$		$\Omega/\text{cm}$
$E_{tp}$	dielectric strength		20		$\text{kV}/\text{mm}$
$\lambda_{tp}$	thermal conductivity		0.8		$\text{W}/(\text{K} \cdot \text{m})$

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.